

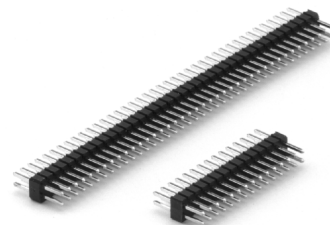
712

Stiftleisten RM 1,27 x 1,27 mm - 2-reihig

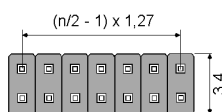
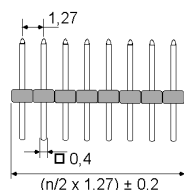
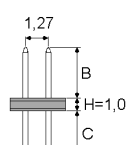
Pin Header Strips Pitch 1,27 x 1,27 mm - Double Row

Technische Daten / Technical Data:

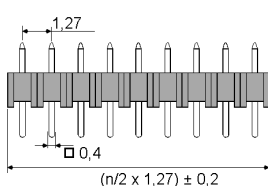
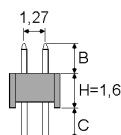
Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	Thermoplastic, rated UL94V0
Kontaktmaterial	Vierkantstift □ 0,40 mm, CuZn 30
Contact Material	Square Pin □ 0,40 mm, CuZn 30
Kontaktoberfläche	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm)
Contact Surface	acc. to options (see below), over Ni (1,3-2,5 µm)
Lötbarkeit	IEC512-12A
Solderability	IEC512-12A
Durchgangswiderstand	≤ 20 mOhm
Contact Resistance	≤ 20 mOhm
Isolationswiderstand	> 5x10 ⁸ Ohm
Insulation Resistance	> 5x10 ⁸ Ohm
Spannungsfestigkeit	500 V _{AC}
Test Voltage	500 V _{AC}
Nennspannung	250 V _{AC}
Current Voltage	250 V _{AC}
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40°C...+105°C
Temperature Range	-40°C...+105°C
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	Reflow-Soldering, further informations in chapter T



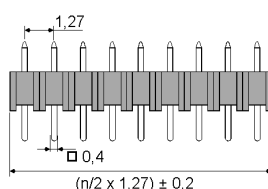
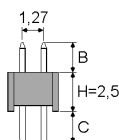
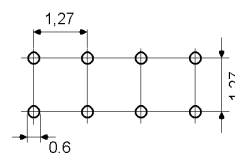
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n = Anzahl Kontakte
n = No. of Contacts



PCB-Layout



Series

Contacts*

Dimensions*

Plating*

712

100

60

60

004-100-pol. zweireihig
double row

10 = B/C/H : 2,70 / 2,60 / 1,00
20 = B/C/H : 3,00 / 3,00 / 1,00
30 = B/C/H : 2,70 / 2,60 / 1,60
40 = B/C/H : 3,00 / 3,00 / 1,60
50 = B/C/H : 2,70 / 2,60 / 2,50
60 = B/C/H : 3,00 / 3,00 / 2,50

50 = verzinkt
tin plated
60 = sel. Au / Sn
duplex plating

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.

* Order example - To be replaced by your specifications.)

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Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Löten
Durchschnitts-Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / Sek. Max.
Vorheizen - Temperatur Min ($T_{s_{min}}$) - Temperatur Max ($T_{s_{max}}$) - Zeit ($t_{s_{min}}$ auf $t_{s_{max}}$)	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (T_p)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (tp)	20-40 Sekunden
Ramp-Dow n Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / second max.
Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Max ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$)	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Dow n Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:
Recommended Reflow-Soldering profile:

